FOR IMMEDIATE DISTRIBUTION

EV GROUP AND THE INSTITUTE OF MICROELECTRONICS IN SINGAPORE PARTNER TO ADVANCE THROUGH-SILICON VIA PROCESS DEVELOPMENT FOR 3D IC INTEGRATION

ST. FLORIAN, AUSTRIA and SINGAPORE, June 14, 2010 – EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, and the Institute of Microelectronics (IME), a research institute of the Agency for Science, Technology and Research (A*STAR), today announced that they have entered into a two-year cooperation agreement to advance 3D IC integration technologies. This joint development is set to establish a 3D IC research and development line at IME's facility in Singapore using EVG's wafer bonding, alignment and lithography systems for 200- and 300-mm through silicon via (TSV) process development. As part of the agreement, EVG will provide IME with process engineering support and access to its demo lab in Austria, while IME will serve as a process hub for EVG's Asia-Pacific customer base.

With this agreement, IME augments its TSV processing capabilities by adding several new EVG systems, including an EVG101 spin and spray coater, an EVG805 semi-automated de-bonder, and an EVG301 wafer cleaner. These systems join the EVG520IS permanent wafer bonder and EVG640 bond aligner already at the facility to enhance IME's 200-mm wafer bonding, mask and bond alignment capabilities for 3D chip stacking.

"As a part of IME's commitment to accelerating the research and development toward 3D IC, we are constantly evaluating equipment on the market that fulfill our process technology objectives," said Dr. Patrick Lo, deputy executive director. "Based on the evaluation results and effective technology support, EV Group is one of our equipment partners of choice as we continue to expand our research and development capabilities. The flexibility of their systems and the process expertise that EVG's team has demonstrated enable us to ramp quickly and scale seamlessly. We look forward to leveraging this partnership to continue to bring the advantages of 3D IC development capabilities to our customers."

Commenting on today's news, EVG corporate technology development and IP director, Markus Wimplinger, noted, "IME is one of the world's leading R&D centers making significant inroads in 3D IC integration, particularly through its work with the 3D Through Silicon Via Consortium. We are thrilled for the opportunity to work closely with this important research institute, which is really taking a lead to boost the research and development of 3D ICs on a global scale. This partnership with IME represents another step forward in EVG's equipment becoming the industry standard for 3D IC manufacturing and significantly expands our reach and presence in the Asia-Pacific region."

About the Agency for Science, Technology and Research (A*STAR)
The Agency for Science, Technology and Research (A*STAR) is the lead agency for fostering world-class scientific research and talent for a vibrant knowledge-based and innovation-driven Singapore. A*STAR oversees 14 biomedical sciences, and physical sciences and engineering research institutes, and nine consortia & center, which are located in Biopolis and Fusionopolis, as well as their immediate vicinity.

A*STAR supports Singapore's key economic clusters by providing intellectual, human and industrial capital to its partners in industry. It also supports extramural research in the universities, hospitals, research centers, and with other local and international partners.

For more information about A*STAR, please visit www.a-star.edu.sg.

-more-

About the Institute of Microelectronics (IME)
The Institute of Microelectronics (IME) is a research institute of the Science and Engineering Research Council of the Agency for Science, Technology and Research (A*STAR). Positioned to bridge the R&D between academia and industry, IME's mission is to add value to Singapore's semiconductor industry by developing strategic competencies, innovative technologies and intellectual property; enabling enterprises to be technologically competitive; and cultivating a technology talent pool to inject new knowledge to the industry. Its key research areas are in integrated circuits design, advanced packaging, bioelectronics and medical devices, MEMS, nanoelectronics, and Silicon photonics.

For more information, visit IME on the Internet: http://www.ime.a-star.edu.sg.

About EV Group
EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume.

The market for Advanced Packaging & 3D Integration solutions represents another high-growth segment in which EVG has successfully established its technology process and expertise. Its dominant position in this market contributed to EVG's financial success in 2009, when the company continued to see an increase in both order intake and revenue despite the global economic recession.

More information is available at www.EVGroup.com.

EV Group Contacts:
Clemens Schütte
Director, Marketing and Communications
EV Group
Tel: +43 7712 5311 0
E-mail: Marketing@EVGroup.com

Karen Do
Account Manager
MCA, Inc.
Tel: +1-650-968-8900, ext. 108
E-mail: kdo@mcapr.com

IME Contact:
Lim Kheng Hwee
Industry Development
Institute of Microelectronics
DID: +65-6770 5316
E-mail: limkh@ime.a-star.edu.sg